

Part Number: XZMDK81FS

 $2.8 \ge 0.8$ mm Right Angle SMD Chip LED Lamp

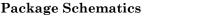
Features

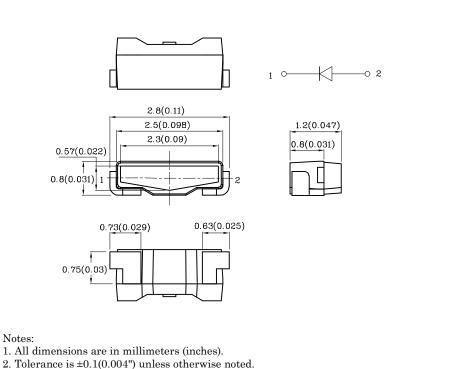
- Ideal for indication light on hand held products
- Long life and robust package
- Standard Package: 2,000pcs/ Reel
- MSL (Moisture Sensitivity Level): 3
- Halogen-free
- RoHS compliant





ATTENTION OBSERVE PRECAUTIONS FOR HANDLING ELECTROSTATIC DISCHARGE SENSITIVE DEVICES





3. Specifications are subject to change without notice.

bsolute Maximum Ratings T _A =25°C)		Red (AlGaInP)	Unit	
Reverse Voltage	V_{R}	5	V	
Forward Current	$\mathbf{I}_{\mathbf{F}}$	30	mA	
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	ifs	185	mA	
Power Dissipation	\mathbf{P}_{D}	75	mW	
Operating Temperature	$T_{\rm A}$	$-40 \sim +85$	°C	
Storage Temperature	Tstg	$-40 \sim +85$		

A Relative Humidity between 40% and 60% is recommended in ESD-protected work areas to reduce static build up during assembly process (Reference JEDEC/JESD625-A and JEDEC/J-STD-033)

Operating Characteristics (T _A =25°C)		Red (AlGaInP)	Unit	
Forward Voltage (Typ.) (I _F =20mA)	V_{F}	1.95	V	
Forward Voltage (Max.) (I _F =20mA)	V_{F}	2.5	V	
Reverse Current (Max.) (V _R =5V)	I_R	10	μΑ	
Wavelength of Peak Emission CIE127-2007*(Typ.) (I _F =20mA)	λP	645*	nm	
Wavelength of Dominant Emission CIE127-2007*(Typ.) (I _F =20mA)	λD	630*	nm	
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =20mA)	$ riangle\lambda$	28	nm	
Capacitance (Typ.) (V _F =0V, f=1MHz)	С	35	$_{\rm pF}$	

Part Number	Emitting Color	Emitting Material	Lens-color	Luminous CIE127 (I _F =20 mo	7-2007* 0mA)	Wavelength CIE127-2007* nm λP	Viewing Angle 20 1/2
				min.	typ.		
XZMDK81FS	Red	AlGaInP	Water Clear	$150 \\ 40*$	297 98*	645*	110°

*Luminous intensity value and wavelength are in accordance with CIE127-2007 standards.

Dec 02,2020



Handling Precautions

Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force. As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might lead to damage and premature failure of the LED.

1.Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.

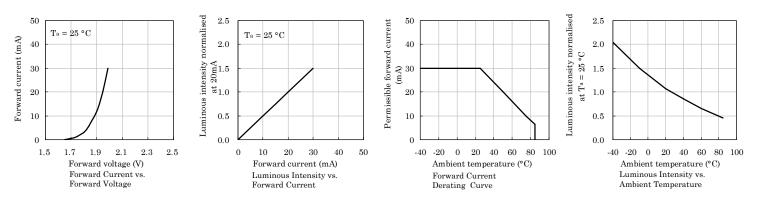


2. As silicone encapsulation is permeable to gases, some corrosive substances such as H_2S might corrode silver plating of leadframe. Special care should be taken if an LED with silicone encapsulation is to be used near such substances.

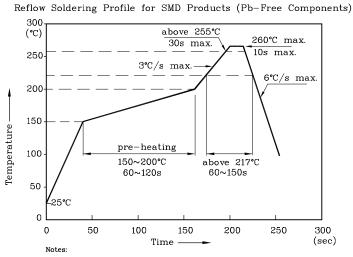


Red 100% $T_a = 25 \text{ °C}$ $T_a = 25 \ ^\circ C$ 15° 309 45 60 75 400 500600 650 700 450550750800 350 90 15° 30° 45° 60° 75° Wavelength (nm) 0° Relative Intensity Vs. CIE Wavelength Spatial Distribution





LED is recommended for reflow soldering and soldering profile is shown below.



1. All temperatures refer to the center of the package,

measured on the package body surface facing up during reflow.

2. Do not apply any stress to the LED during high temperature conditions. 3. Maximum number of soldering passes: 2

1.0

0.5

0.0

909



1.4

0.5

0.9

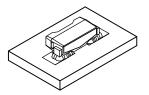
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0.9 0.2

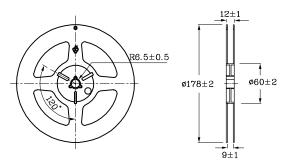
0.5

The device has a single mounting surface. The device must be mounted according to the specifications.

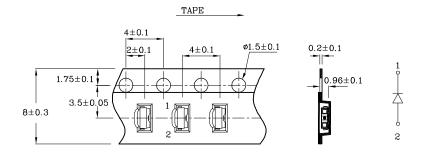
Recommended Soldering Pattern (Units : mm; Tolerance: ± 0.1)



Reel Dimension (Units : mm)



✤ Tape Specification (Units : mm)



Remarks:

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm

2. Luminous intensity / luminous flux: +/-15%

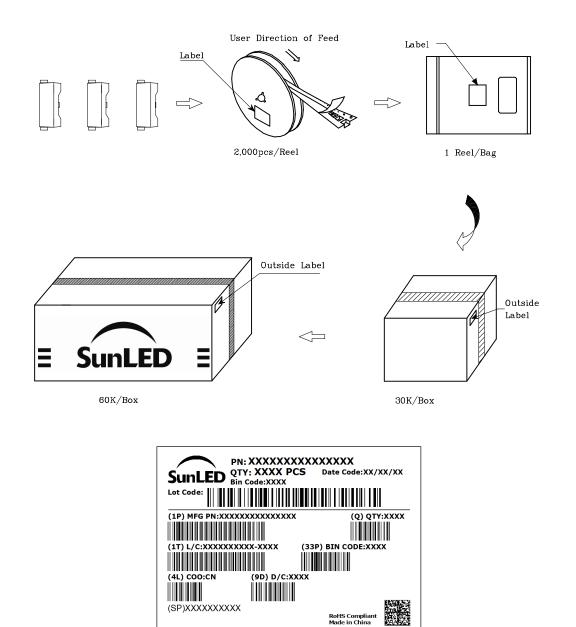
3. Forward Voltage: +/-0.1V $\,$

Note: Accuracy may depend on the sorting parameters.

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PACKING & LABEL SPECIFICATIONS



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- 2. Contents within this document are subject to improvement and enhancement changes without notice.
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- User accepts full risk and responsibility when operating the product(s) beyond their intended specifications.
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- $6. \ Additional \ technical \ notes \ are \ available \ at \ \underline{https://www.SunLEDusa.com/TechnicalNotes.asp}$

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